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AMENDMENT
U.S. Serial No. 10/636,066

AMENDMENTS TO THE CLAIMS

This listing of claims replaces all prior versions, and listings, of claims in the application.

Claims 1-8 (cancelled)

9. (Previously Presented) A device comprising a molded electronic component designed to comply with preset operating characteristics comprising a substrate for holding passive circuit elements and a material molded about the substrate and circuit elements, wherein the interaction of the material and the circuit elements forms a circuit causing the component to perform at the preset operating characteristics.

10. (Original) The molded electronic component of claim 9, wherein the material forms a housing that is marked with indicia to indicate an operating characteristic associated with the component.

11. (Original) The molded electronic component of claim 10, further comprising the housing containing means for interfacing with a piece of equipment selected from the group consisting of CATV equipment, telecommunications equipment, consumer electronics equipment, and computer equipment.

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12. (Original) The molded electronic component of claim 9, wherein the passive circuit elements form an equalizer and further comprising pins coupled to one or more of the passive circuit elements and adapted to interface the equalizer with a predetermined location in a CATV amplifier.

13. (Original) The molded electronic component of claim 9, wherein the passive circuit elements form an equalizer, an attenuator, or a duplex filter.

14. (Original) A method for making an encapsulated electronic component comprising :

- (a) designing a circuit to operate at a first set of operating characteristics;
- (b) encapsulating the circuit in a particular material;
- (c) retesting the encapsulated circuit to determine a second set of operating characteristics;
- (d) determining whether the second set of operating characteristics matches a predetermined set of operating characteristics for the encapsulated component; and
- (e) modifying, if necessary, the design of the circuit to account for the effect of the encapsulating material so that the overall encapsulated component performs at the predetermined set of operating characteristics.